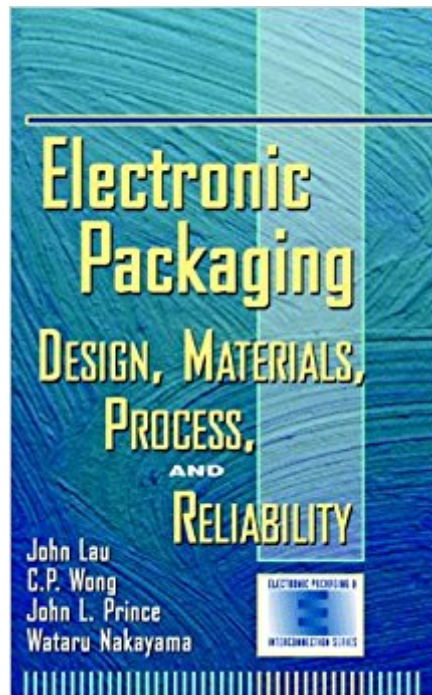




Ebook Directory
the best source of ebook

The book was found

Electronic Packaging: Design, Materials, Process, And Reliability



Synopsis

The ultimate, up-to-the-minute electronic packaging resource The ever-increasing pin counts and clock speeds of modern electronics continue to "push the performance envelope" with regard to designing packaging and interconnection solutions that can meet increasingly challenging requirements. Here's the help you need! For the first time, four well-known experts representing the four relevant fields--mechanical engineering, electrical engineering, thermal management, and materials--team up to provide a single-volume comprehensive reference that explains packaging and interconnection basics, details design tradeoff considerations, and presents specific system-level solutions. This unprecedented and unsurpassed multi-disciplinary coverage not only includes all the new technologies--BGA, Flip Chip, DCA, and CSP--it shows how they can be most effectively integrated. With its clear explication of both theoretical and practical issues, Electronic Packaging will be of considerable and continuing value if you hope to design and/or refine more reliable, robust, and cost-effective packaging solutions for virtually any interconnect system.

Book Information

Series: Electronic Packaging and Interconnection Series

Hardcover: 496 pages

Publisher: McGraw-Hill Professional; 1 edition (February 1, 1998)

Language: English

ISBN-10: 0070371350

ISBN-13: 978-0070371354

Product Dimensions: 6.5 x 1.6 x 9.1 inches

Shipping Weight: 1.9 pounds

Average Customer Review: Be the first to review this item

Best Sellers Rank: #697,749 in Books (See Top 100 in Books) #148 in [Books > Textbooks > Engineering > Electrical & Electronic Engineering](#) #1470 in [Books > Engineering & Transportation > Engineering > Electrical & Electronics > Electronics](#) #4533 in [Books > Computers & Technology > Networking & Cloud Computing](#)

Customer Reviews

The ultimate, up-to-the-minute electronic packaging resource! Electronic Packaging The ever-increasing pin counts and clock speeds of modern electronics continue to "push the performance envelope" with regard to designing packaging and interconnection solutions that can meet increasingly challenging requirements. The fast SRAMS for cache memories need to perform

at near-microprocessor speeds to prevent data bottlenecks. ASICs are expected to run faster than 200 MHz on-chip clock frequency and have up to 900 package pin counts--and, for many telecommunication products, even more. Here's the help you need! For the first time, four well-known experts representing the four relevant fields--mechanical engineering, electrical engineering, thermal management, and materials--team up to provide a single-volume comprehensive reference that explains packaging and interconnection basics, details design tradeoff considerations, and presents specific system-level solutions. This unprecedented and unsurpassed multi-disciplinary coverage not only includes all the new technologies--BGA, Flip Chip, DCA, and CSP--it shows how they can be most effectively integrated. Among the topics explored: How to design, analyze, and measure electronic packaging and interconnections; Basic electrical and heat transfer effects and how to accommodate them; Thermal, electrical, and mechanical analysis and design techniques; What causes stresses and strains and how to reduce them; Currently used and advanced materials and processes. With its clear explication of both theoretical and practical issues, *Electrical Packaging* will be of considerable and continuing value for any professional seeking to design and/or refine more reliable, robust, and cost-effective packaging solutions for virtually any interconnect system.

Dr. John H. Lau is President of Express Packaging Systems, Inc. He previously worked for Hewlett-Packard Company. Dr. C.P. Wong is a professor of Materials Science and Engineering at the Georgia Institute of Technology. He is a past President of the IEEE-CPMT Society and has done research at AT&T. Dr. John Prince is Professor of Electrical and Computer Engineering and Director of the Center for Electronic Packaging Research at the University of Arizona. Dr. Warren Nakayama is a professor at the CALCE Electronic Packaging Research Center at the University of Maryland. He previously worked for Hitachi Ltd.

[Download to continue reading...](#)

Electronic Packaging: Design, Materials, Process, and Reliability Handbook of Organic Materials for Optical and (Opto)Electronic Devices: Properties and Applications (Woodhead Publishing Series in Electronic and Optical Materials) The Science and Technology of Flexible Packaging: Multilayer Films from Resin and Process to End Use (Plastics Design Library) IEEE Guide to the Collection and Presentation of Electrical, Electronic, Sensing Component, and Mechanical Equipment Reliability Data for Nuclear-Pow (IEEE Std 500-1977) Reliability of RoHS-Compliant 2D and 3D IC Interconnects (Electronic Engineering) Encapsulation Technologies for Electronic Applications (Materials and Processes for Electronic Applications) Managing Risk and Reliability of Process

Plants Semiconductor Process Reliability in Practice Engineering Materials 3: Materials Failure Analysis: Case Studies and Design Implications (International Series on Materials Science and Technology) (v. 3) Electronic, Magnetic, and Optical Materials, Second Edition (Advanced Materials and Technologies) Organic Electronic Materials: Conjugated Polymers and Low Molecular Weight Organic Solids (Springer Series in Materials Science) Solder Joint Reliability Assessment: Finite Element Simulation Methodology (Advanced Structured Materials) Materials for Optoelectronics (Electronic Materials: Science & Technology) Package Design Workbook: The Art and Science of Successful Packaging Structural Packaging: Design Your Own Boxes and 3D Forms Graphic Design Success: Over 100 Tips for Beginners in Graphic Design: Graphic Design Basics for Beginners, Save Time and Jump Start Your Success (graphic ... graphic design beginner, design skills) Packaging Design: Successful Product Branding From Concept to Shelf H-Point 2nd Edition: The Fundamentals of Car Design & Packaging Electrodeposition: The Materials Science of Coatings and Substrates (Materials Science and Process Technology) Probability, Reliability, and Statistical Methods in Engineering Design

[Contact Us](#)

[DMCA](#)

[Privacy](#)

[FAQ & Help](#)